

/ Descriptions

50~1000V

25A GBJ

Glass Passivated Bridge Rectifiers, Reverse Voltage:50~1000V,Forward Current:25A,GBJ package.

/ Features

PCB

UL

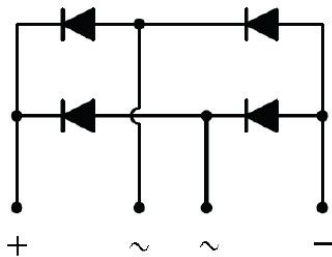
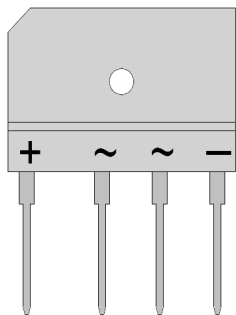
94V-0

Ideal for printed circuit board, Case material molded plastic, The plastic material has U/L flammability classification 94V-0. Halogen free product.

/ Applications

一般用途.

General purpose.

/ Equivalent Circuit**/ Pinning**

1 2 3 4

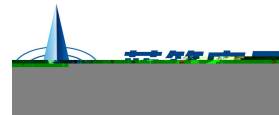
PIN1 DC+ PIN2 AC PIN 3 AC PIN 4 DC-

/ h_{FE} Classifications & Marking

See Marking Instructions

GBJ25005~GBJ2510

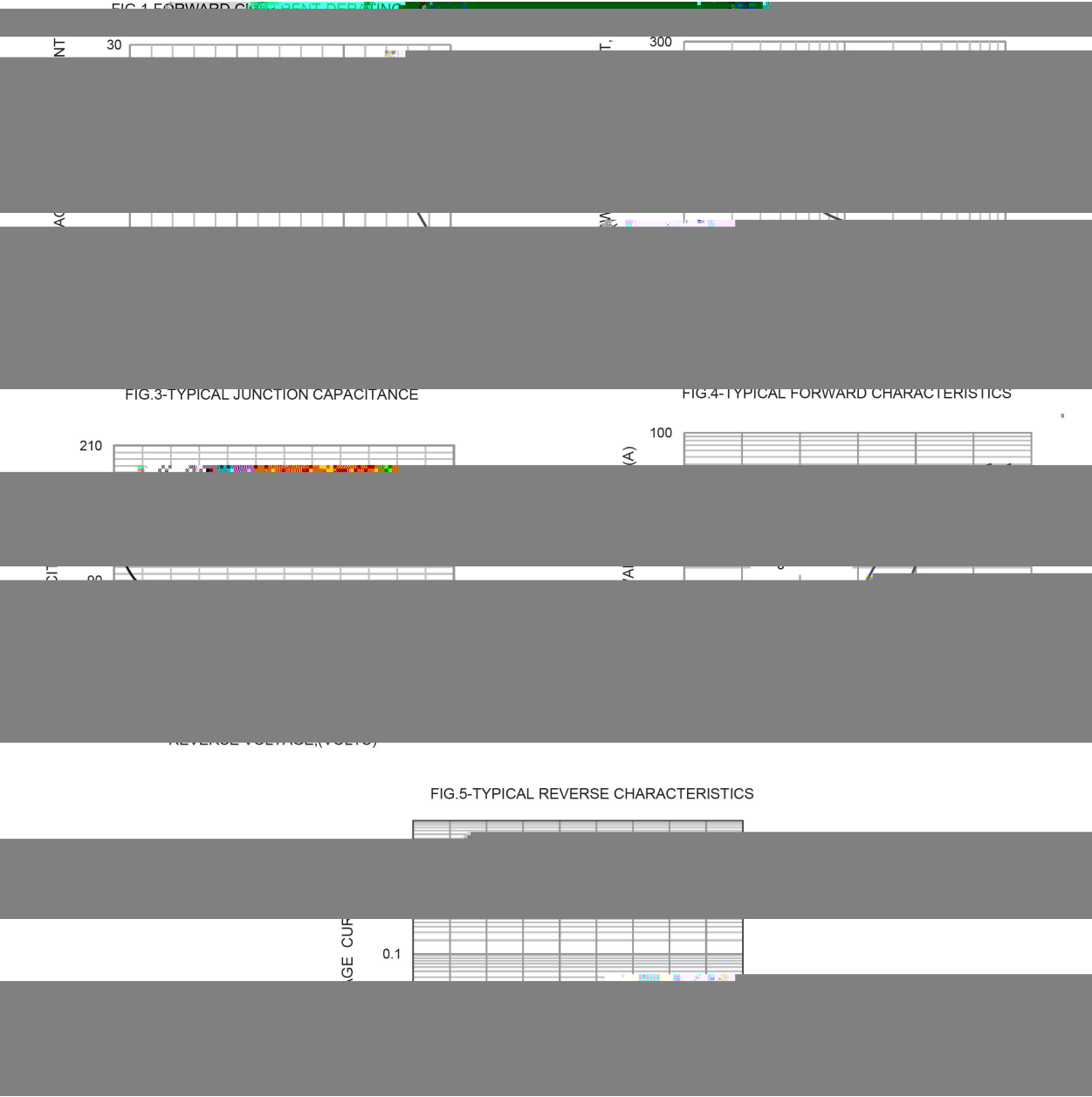
Rev.A .Jul.-2018



DATA SHEET

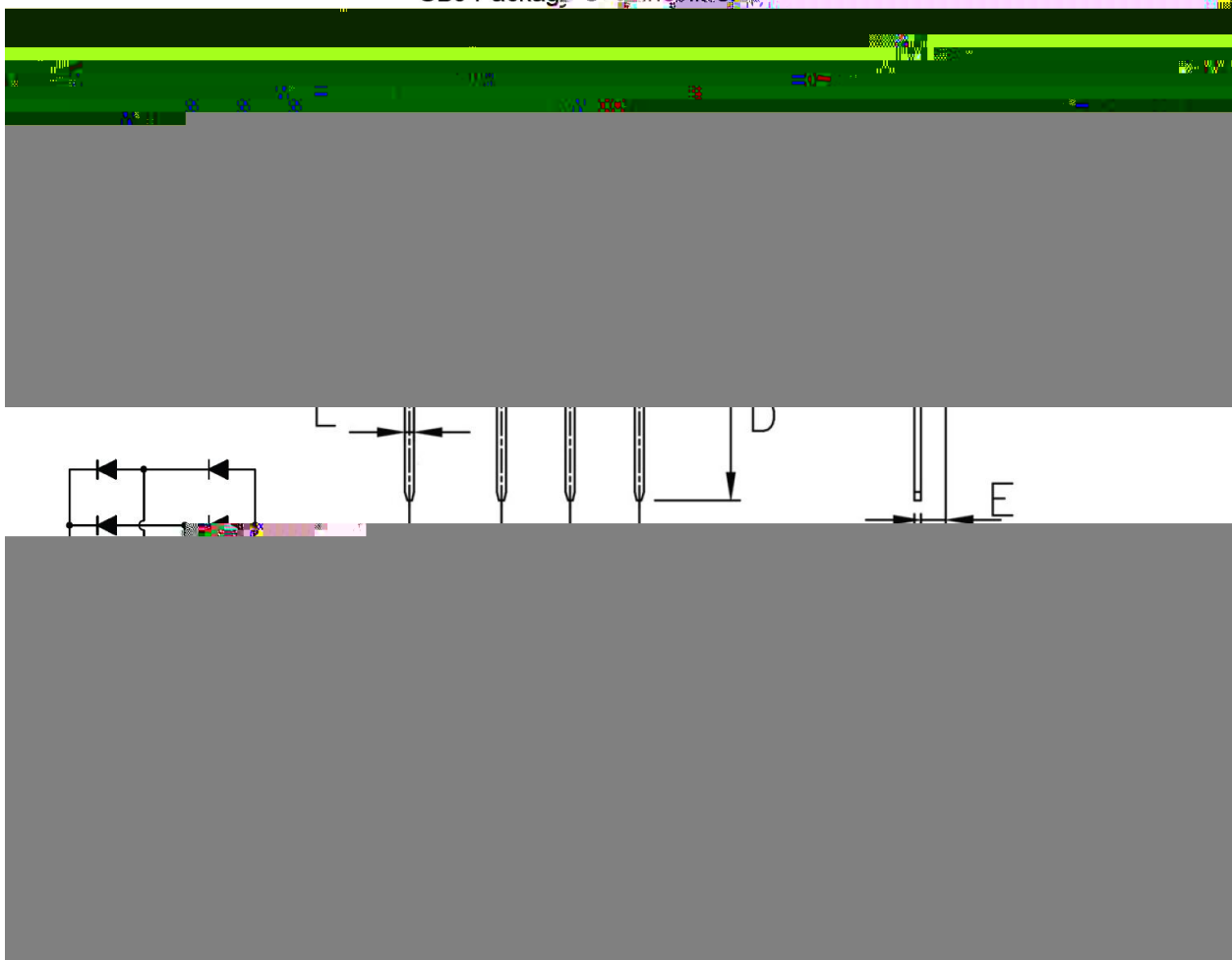
Parameter	Symbol	Rating							Unit
		GBJ 25005	GBJ 2501	GBJ 2502	GBJ 2504	GBJ 2506	GBJ 2508	GBJ 2510	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current (with heatsink Note 2) Peak Forward Surge Current 8.3ms Single Half Sine-Wave	$I_{F(AV)}$	25							A

/ Electrical Characteristic Curve

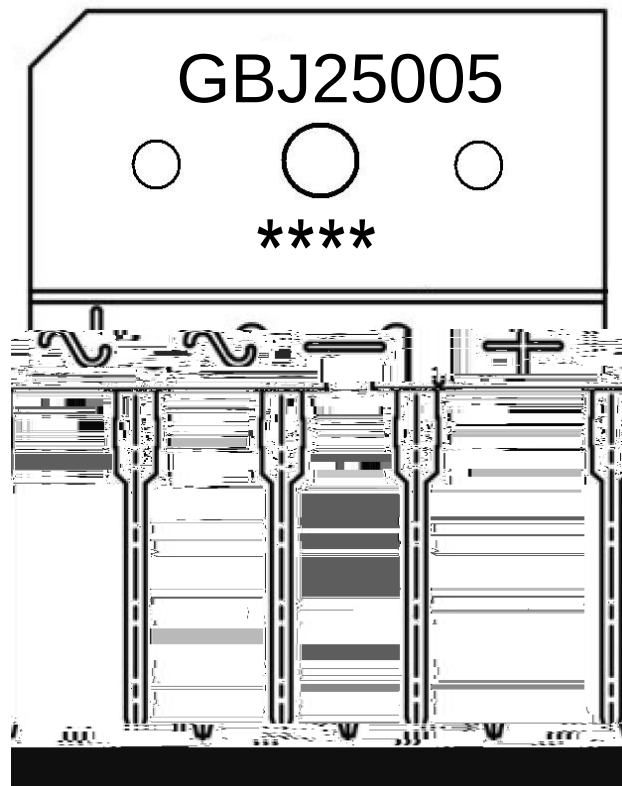


/ Package Dimensions

GBJ Package Outline Dimensions



/ Marking Instructions



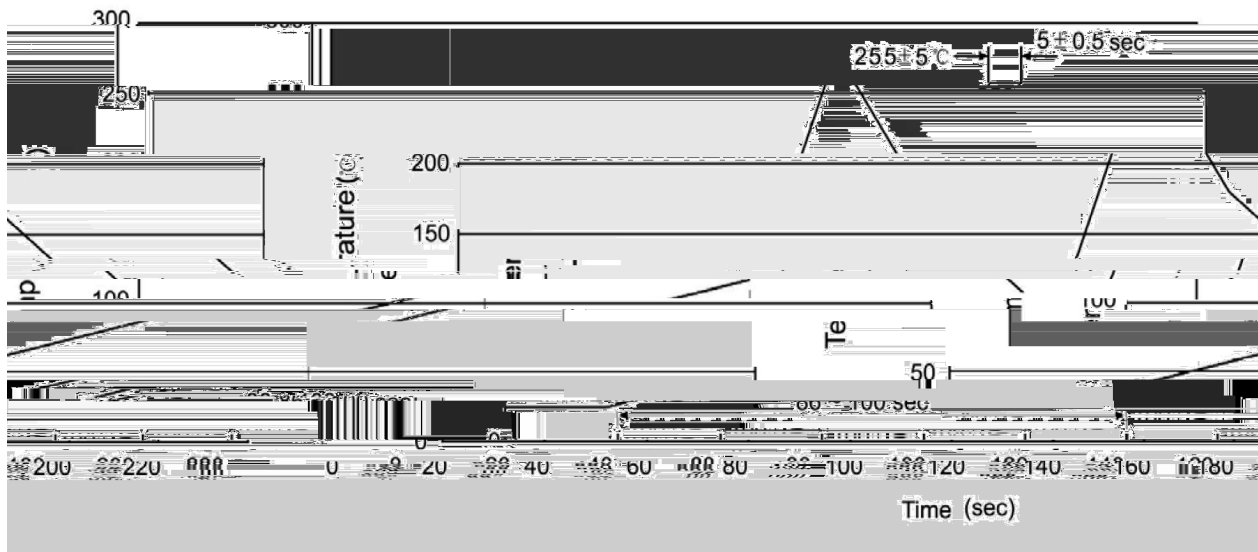
GBJ25005

Note:

GBJ25005: Product Type.

*****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

/ Resistance to Soldering Heat Test Conditions

温度：270±5°C

时间：10±1 sec.

Temp.:270±5°C

Time:10±1 sec

/ Packaging SPEC.

散件包装